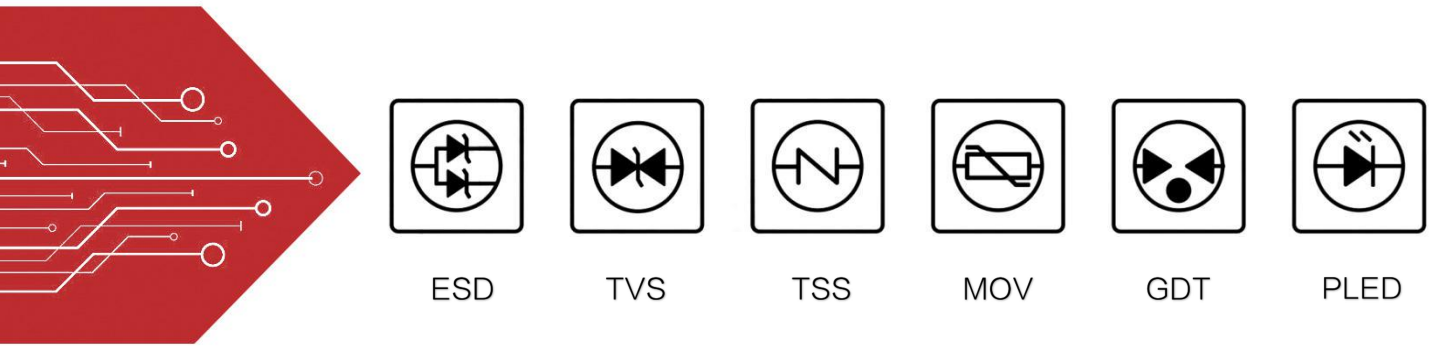
MSKSEMI
SEMICONDUCTOR



Product data sheet

www.msksemi.com

SMA

Features

- Plastic package has Underwriters Laboratories Flammability Classification 94V-0
- Glass passivated chip junction
- For surface mount application
- Low profile package
- Built-in strain relief, ideal for automated placement

Mechanical Data

- **Case:** SMA (DO-214AC), molded plastic
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denotes cathode end

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Characteristic	Symbol	S1A	S1B	S1D	S1G	S1J	S1K	S1M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @T_L = 100°C	I_O	1.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Forward Voltage @I_F = 1.0A	V_{FM}	1.10							V
Peak Reverse Current @T_A = 25°C At Rated DC Blocking Voltage @T_A = 125°C	I_{RM}	5.0 200							μA
Typical Junction Capacitance (Note 2)	C_j	15							pF
Typical Thermal Resistance (Note 3)	$R_{\theta JL}$	30							°C/W
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +175							°C

Note: 1. Measured with I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A,
2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.
3. Mounted on P.C. Board with 8.0mm² land area.

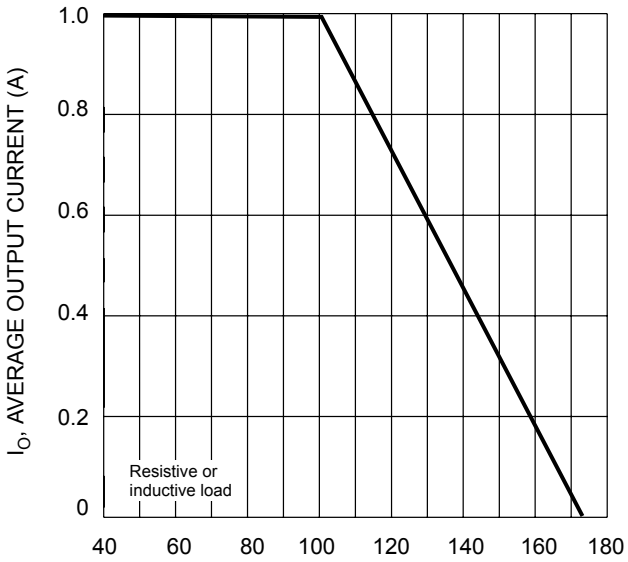


Fig. 1 Forward Current Derating Curve

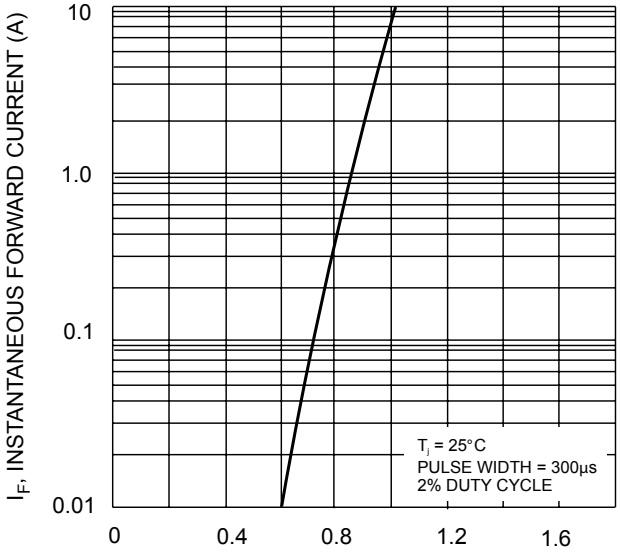


Fig. 2 Typical Forward Characteristics

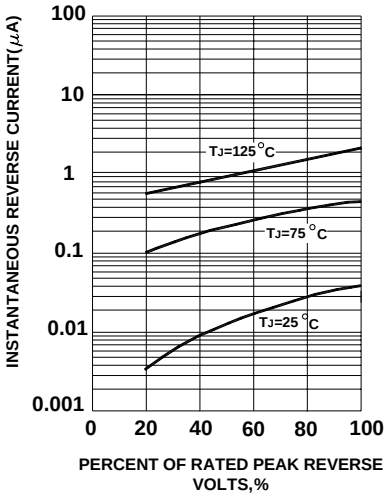


FIG.3-TYPICAL REVERSE CHARACTERISTICS

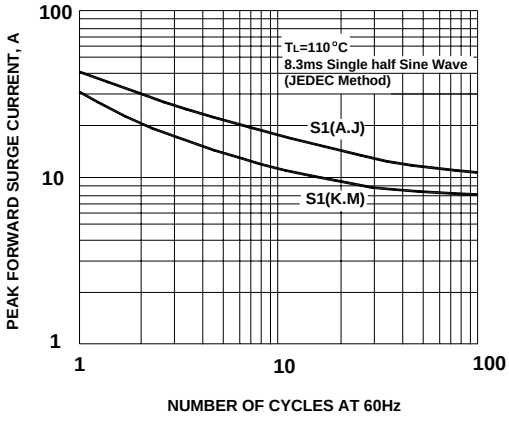


FIG.4- PEAK FORWARD SURGE CURRENT

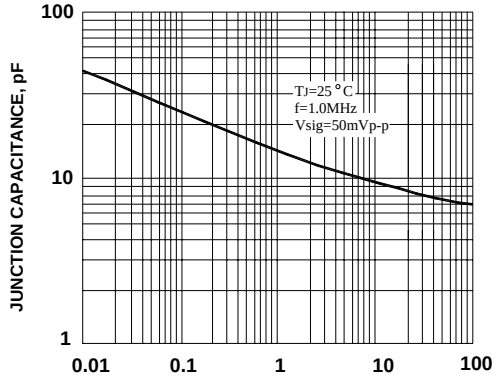
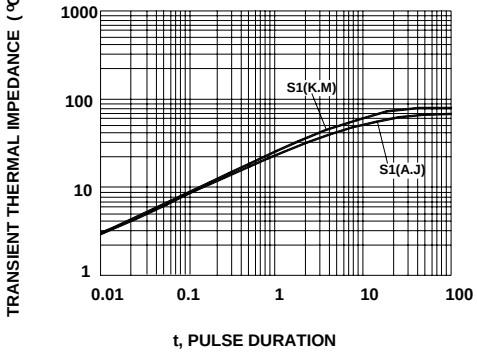
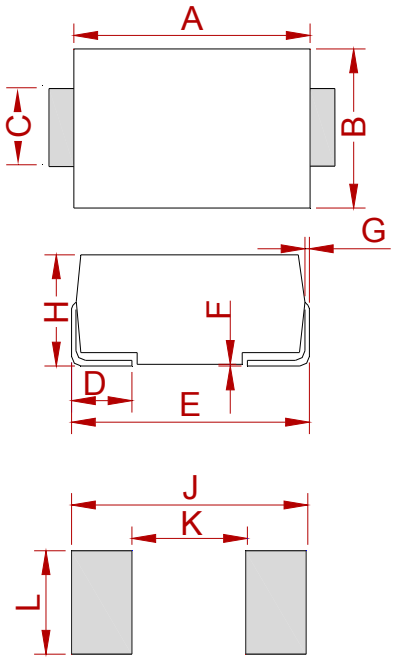


FIG.5- TYPICAL JUNCTION CAPACITANCE

FIG.6- TRANSIENT THERMAL IMPEDANCE



PACKAGE MECHANICAL DATA



DO-214AC (SMA)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
S1A THRU S1M	SMA	2000

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